

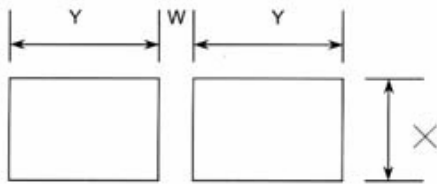


ALUMINUM ELECTROLYTIC CAPACITOR

Unit: mm

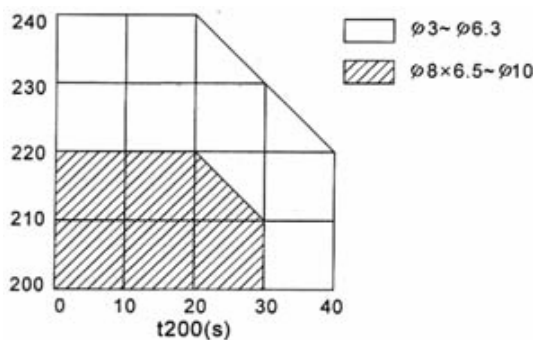
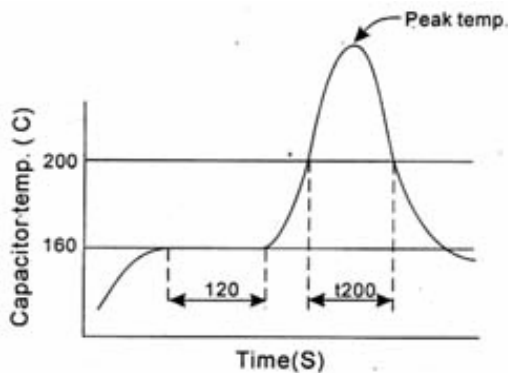
SURFACE MOUNT TYPE

Recommended pad pattern and size



Recommended soldering methods

Method	Reflow soldering	Soldering iron	Flow soldering
Advisability	○ Recommended	○ Recommended	✗ Not Recommended



D φ x L	Case Code	Land Size		
		X	Y	W
4x5.3	D55	1.6	2.6	1.0
4x5.7	D60	1.6	2.6	1.0
5x5.3	E55	1.6	3.0	1.4
5x5.7	E60	1.6	3.0	1.4
6.3x5.3	F55	1.6	3.5	1.9
6.3x5.7	F60	1.6	3.5	1.9
6.3x7.7	F80	1.6	3.5	1.9
8x6.5	G68	1.6	4.0	2.1
8x10	G10	2.5	3.5	3.0
10x10	H10	2.5	4.0	4.0

(1) Reflow soldering condition.

The following temperature profile condition should be observed for soldering. (For higher temperature, please contact us after measuring the capacitor's product temperature profile at your side.)

Product temperature will rise slower as the product size gets bigger. It is not necessary to adjust the reflow furnace temperature setting according to the product size, for example, φ 4 and φ 10 products can be mixed on one PCB for reflowing.

(2) Soldering precautions

1. Elements related to the reflow soldering temperature
 - *Product size: The temperature rises slower as the size gets bigger.
 - *Product location: The center part of the PCB tends to have a lower temperature than the PCB edges.
 - *PCB size: The PCB temperature rises slower as the area and / or thickness of the PCB gets greater.
2. Repeated reflowing
 - *Avoid reflowing twice if possible.
 - *If repeated reflowing is unavoidable, contact us after measuring the first and the second reflow profiles and reflow interval at your side.
 - *Do not attempt to reflow three times.
3. Soldering with soldering iron
 - Observe the following conditions.
 - *The iron tip temperature : 350 ±5°C
 - *Soldering time: 3 seconds.